

PART II

Product name	Parameter	Specification
Sapphire wafers 6" Diameter 150 mm +/- 0.3 mm Thickness: 650 μm +/- 20 μm	Growth method	Kyropolos
	Orientation:	C-Plane (0001) surface orientation $\pm 0.3^\circ$
	Surface Finish:	Front side polished
	TTV	<10 μm
	BOW	<15 μm
	Packaging:	Cassette